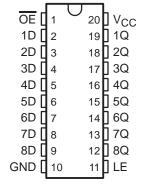
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- BiCMOS Technology With Low Quiescent Power
- Buffered Inputs
- Input/Output Isolation From V_{CC}
- Controlled Output Edge Rates
- 48-mA Output Sink Current
- Output Voltage Swing Limited to 3.7 V
- SCR Latch-Up-Resistant BiCMOS Process and Circuit Design
- 3-State Outputs Directly Drive Bus Lines
- Package Options Include Plastic Small-Outline (M) and Shrink Small-Outline (SM) Packages and Standard Plastic (E) DIP

CD74FCT573...M OR SM PACKAGE CD74FCT573AT...E PACKAGE (TOP VIEW)



description

The CD74FCT573 and CD74FCT573AT are octal, transparent, D-type latches, designed using a small-geometry BiCMOS technology. The output stage is a combination of bipolar and CMOS transistors that limits the output high level to two diode drops below V_{CC} . This resultant lowering of output swing (0 V to 3.7 V) reduces power-bus ringing [a source of electromagnetic interference (EMI)] and minimizes V_{CC} bounce and ground bounce and their effects during simultaneous output switching. The output configuration also enhances switching speed and is capable of sinking 48 mA.

When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is low, the Q outputs are latched at the logic levels of the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The CD74FCT573 and CD74FCT573AT are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each latch)

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q ₀
Н	Χ	Χ	z

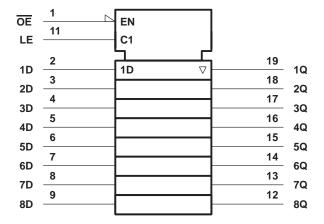


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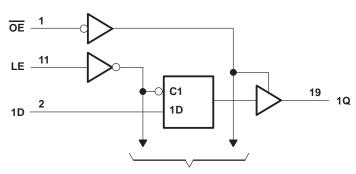
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

DC supply voltage range, V _{CC}		0.5 V to 6 V
DC input clamp current, I_{IK} ($V_I < -0.5 \text{ V}$)		–20 mA
DC output clamp current, I_{OK} ($V_O < -0.5 \text{ V}$)		–50 mA
DC output sink current per output pin, IOL		70 mA
DC output source current per output pin, IOH .		–30 mA
Continuous current through V _{CC} , I _{CC}		140 mA
Continuous current through GND		400 mA
Package thermal impedance, θ_{JA} (see Note 1):	E package	69°C/W
	M package	58°C/W
	SM package	70°C/W
Storage temperature range, T _{stg}		\dots -65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (see Note 2)

		MIN	MAX	UNIT
Vcc	Supply voltage	4.75	5.25	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
٧ _I	Input voltage	0	VCC	V
٧o	Output voltage	0	VCC	V
IOH	High-level output current		-15	mA
loL	Low-level output current		48	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V
TA	Operating free-air temperature	0	70	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T _A = 25°C	MIN MAX	UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN MAX	WIIN WAX	UNII
VIK	$I_{I} = -18 \text{ mA}$	4.75 V	-1.2	-1.2	V
VOH	$I_{OH} = -15 \text{ mA}$	4.75 V	2.4	2.4	V
VOL	I _{OL} = 48 mA	4.75 V	0.55	0.55	V
lį	$V_I = V_{CC}$ or GND	5.25 V	±0.1	±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.25 V	±0.5	±10	μΑ
los†	$V_I = V_{CC}$ or GND, $V_O = 0$	5.25 V	-60	-60	mA
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.25 V	8	80	μΑ
ΔI _{CC} ‡	One input at 3.4 V, Other inputs at V _{CC} or GND	5.25 V	1.6	1.6	mA
Ci	$V_I = V_{CC}$ or GND		10	10	pF
Co	$V_O = V_{CC}$ or GND		15	15	pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 100 ms.

timing requirements over recommended operating temperature conditions (unless otherwise noted) (see Figure 1)

				CT573	CD74FCT573AT		UNIT
			MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration	LE high	6		5		ns
t _{su}	Setup time	Data before LE↓	2		2		ns
t _h	Hold time	Data after LE↓	1.5		1.5		ns



[‡] This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

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switching characteristics over recommended operating conditions, $T_A = 25^{\circ}C$ (unless otherwise noted) (see Figure 1)

			CD74FCT573			CD74FCT573AT			
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C	MIN	MAX	T _A = 25°C	MIN	MAX	UNIT
	(1141 01)	(0011 01)	TYP	IVIIIV	WAX	TYP		IVIAA	
	D	Q	5	1.5	8	3.9	1.5	5.7	
^t pd	LE		9	2	13	4.4	2	7	ns
t _{en}	ŌĒ	Q	7	1.5	12	6	1.5	8	ns
^t dis	ŌĒ	Q	6	1.5	7.5	4	1.5	5.8	ns

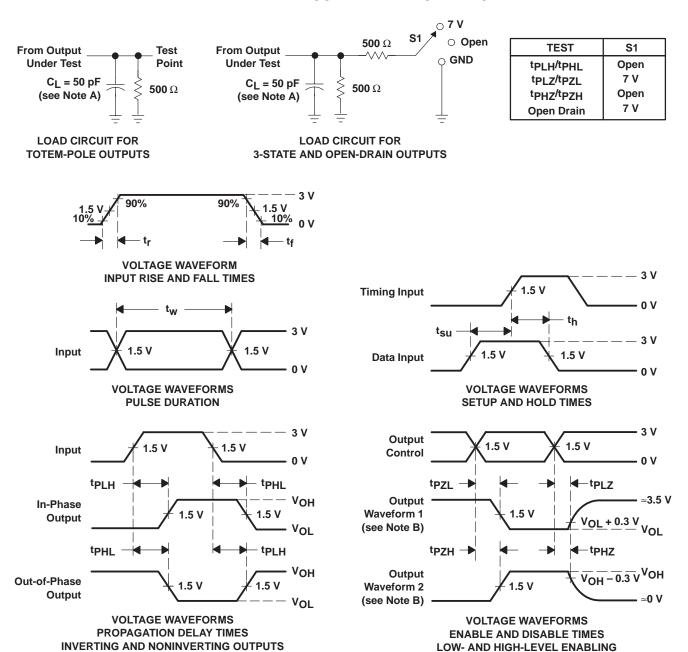
noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C

	PARAMETER	MIN	TYP	MAX	UNIT
VOL(P)	Quiet output, maximum dynamic VOL		1		V
VOH(V)	Quiet output, minimum dynamic VOH		0.5		V
VIH(D)	High-level dynamic input voltage	2			V
V _{IL(D)}	Low-level dynamic input voltage			0.8	V

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS		TYP	UNIT
C _{pd} Power dissipation capacitance	No load,	f = 1 MHz	34	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, t_f and $t_f = 2.5$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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